

What is claimed is:

1. A wiring board comprising:

a substrate;

5 a bank which is disposed above the substrate to provide a plurality of regions;
and

a conductive layer and first and second interconnecting lines formed between
the substrate and the bank, wherein:

the bank has a top surface and a pair of side surfaces provided on both sides of
10 the top surface; and
the side surfaces slopes symmetrically with respect to the substrate.

2. The wiring board as defined in claim 1, wherein:

the first interconnecting line is formed in a position closer to the substrate than
15 the second interconnecting line, and the vertical centerline of the first interconnecting
line is not coincide with the vertical centerline of the second interconnecting line;

the conductive layer is formed in a position closer to the substrate than the
second interconnecting line, and the vertical centerline of the conductive layer is not
coincide with the vertical centerline of the second interconnecting line; and

20 the conductive layer and the first interconnecting line respectively have
portions which are not located under the second interconnecting line, and the portions
extend in opposite width directions.

3. The wiring board as defined in claim 2,

25 wherein the lengths of the portions of the conductive layer and the first
interconnecting line not located under the second interconnecting line are equal.

4. The wiring board as defined in claim 2,
wherein the second interconnecting line is disposed right under the bank and
within a range corresponding to the distance between the side surfaces of the bank.

5 5. The wiring board as defined in claim 4, wherein:
the bank includes a first bank portion formed of an inorganic material, and a
second bank portion formed of an organic material on the first bank portion; and
the second interconnecting line is disposed right under the first and second
bank portions within a range corresponding to the distance between the side surfaces of
10 the bank.

6. The wiring board as defined in claim 4, wherein:
a depression is formed in the substrate; and
the conductive layer and the first interconnecting line are disposed within the
15 depression so as not to project above the surface of the substrate.

7. The wiring board as defined in claim 1,
wherein the conductive layer is one of electrodes of a capacitor.

20 8. The wiring board as defined in claim 1,
wherein the first and second interconnecting lines are respectively a signal line
and a power supply line.

9. The wiring board as defined in claim 1, wherein:
25 the first interconnecting line constitutes a part of a first drive circuit; and
the conductive layer and the second interconnecting line constitute a part of a
second drive circuit.

10. The wiring board as defined in claim 6, wherein:
the first interconnecting line constitutes a part of a first drive circuit; and
the conductive layer and the second interconnecting line constitute a part of a
5 second drive circuit.

11. An electro-optical device comprising:
the wiring board as defined in claim 1; and
a functional layer disposed in each of the regions provided by the bank .

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12. An electro-optical device comprising:
the wiring board as defined in claim 6; and
a functional layer disposed in each of the regions provided by the bank .

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13. An electro-optical device comprising:
the wiring board as defined in claim 10; and
a functional layer disposed in each of the regions provided by the bank .

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14. An electronic instrument comprising the electro-optical device as defined in
claim 11.

15. An electronic instrument comprising the electro-optical device as defined in
claim 12.

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16. An electronic instrument comprising the electro-optical device as defined in
claim 13.

17. A method of manufacturing an electro-optical device comprising:
forming the wiring board as defined in claim 1; and
forming a functional layer by disposing a liquid material including a functional
layer material in each of the regions provided by the bank.

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18. A method of manufacturing an electro-optical device comprising:
forming the wiring board as defined in claim 6; and
forming a functional layer by disposing a liquid material including a functional
layer material in each of the regions provided by the bank.

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19. A method of manufacturing an electro-optical device comprising:
forming the wiring board as defined in claim 10; and
forming a functional layer by disposing a liquid material including a functional
layer material in each of the regions provided by the bank.

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